



(11) **EP 2 374 612 A8**

(12) **CORRECTED EUROPEAN PATENT APPLICATION**
published in accordance with Art. 153(4) EPC

(15) Correction information:
Corrected version no 1 (W1 A1)
Corrections, see
Bibliography INID code(s) 72

(51) Int Cl.:
B32B 15/08 (2006.01) **H05K 3/38** (2006.01)

(86) International application number:
PCT/JP2009/070543

(48) Corrigendum issued on:
28.12.2011 Bulletin 2011/52

(87) International publication number:
WO 2010/073903 (01.07.2010 Gazette 2010/26)

(43) Date of publication:
12.10.2011 Bulletin 2011/41

(21) Application number: **09834706.5**

(22) Date of filing: **08.12.2009**

(84) Designated Contracting States:
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR
HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL
PT RO SE SI SK SM TR

(30) Priority: **26.12.2008 JP 2008334170**

(71) Applicant: **FUJIFILM Corporation**
Tokyo 106-8620 (JP)

(72) Inventor: **SATOU, Masataka**
Ashigarakami-gun
Kanagawa 258-8577 (JP)

(74) Representative: **HOFFMANN EITLE**
Patent- und Rechtsanwälte
Arabellastraße 4
81925 München (DE)

(54) **SURFACE METAL FILM MATERIAL, PROCESS FOR PRODUCING SURFACE METAL FILM MATERIAL, PROCESS FOR PRODUCING METAL PATTERN MATERIAL, AND METAL PATTERN MATERIAL**

(57) A surface metal film material including, in this order, a substrate, a polymer layer that receives a plating catalyst or a precursor thereof, and a metal film formed by plating, wherein, when $x \mu\text{m}$ represents surface roughness (Ra) at an interface between the substrate

and the polymer layer, and $y \mu\text{m}$ represents surface roughness (Ra) at an interface between the polymer layer and the metal film, $x > y$ and $5 \mu\text{m} > x > 0.1 \mu\text{m}$.

EP 2 374 612 A8